

## NMC508C SILICON ETCH SYSTEM

### System Overview

The NMC508C is an ICP high-density plasma dry etching tool used for silicon etching of 200 mm wafers predominantly in Power and Logic ICs. It is a fully automated multi-chamber cluster tool capable of serial or parallel processing.

<b>Substrate Size:</b>	200 mm
<b>Applications compounds:</b>	Silicon
<b>Technology Markets:</b>	Digital IC, Power IC, Analog IC

### Processes

- Shallow trench isolation (STI) etch
- Polysilicon gate etch
- Deep trench etch
- Contact trench etch
- Tungsten gate etch
- Floating gate etch
- Etch back
- Zero mark etch

### Production Advantages

- Planar ICP with automatic matching and magnetic shield generates high plasma uniformity across the wafer
- Independent control of center and edge gas injection optimizes etch rate uniformity
- Symmetrical lining design provides better etch uniformity
- Robust end point detection system maximizes signal-to-noise performance



NMC 508C Silicon Etcher